

Technical Data Sheet

EP-2009-6-H-117

B-Stageable Adhesive

Introduction:

EP-2009-6-H-117 is designed for use in laminate-based application. This material is ideal for sealing of glass / metal with various substrates in IC / LED/ Electronic application where bleed needs to be minimized.

Features

- Dispense by write
- Low moisture uptake
- Low warpage

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Density	1.25 g/cc	Pycnometer	FT-P001
Appearance	black		
Viscosity @ 25°C	30000– 35000 cps	Brookfield DV-III/CP-51 @ 5rpm	FT-P006
Thixotropic Index @ 25°C	3.4 – 3.8	Brookfield DV-III/CP-51 Visc @ 0.5rpm/Visc @ 5rpm	FT-P008
Grind	< 20µm	Grindmeter	FT-P025
Work Life @ 25°C	48 hours	25% increase in visc. @ 5rpm	FT-P024
Shelf Life @ -40°C to -15 °C	6 months		FT-P018
CURE CONDITION		TEST DESCRIPTION	TEST METHOD
B-stage Cure Condition		40 - 60 min @ 80 - 100 °C depending on the oven efficiency	
C-stage Cure Condition		90 - 120 min @170-175 °C (The higher temperature and the longer cure time, the higher Tg results)	
MECHANICAL PROPERTIES-POST CURE		TEST DESCRIPTION	TEST METHOD
Die Shear Strength @ 25°C		12 Kg/die	2x2mm Si die on Microscope Slide Glass
			FT-M012

Die Shear Strength @260°C 3 Kg/die	2x2mm Si die on Microscope Slide Glass	FT-M012
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The tables shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

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PHYSIOCHEMICAL PROPERTIES- POST CURE	TEST DESCRIPTION	TEST METHOD
Glass Transition Temperature 89 °C	DMA 3 Point Bending Mode	FT-M014
Coefficient of Thermal Expansion	TMA Expansion Mode	FT-M016
Below Tg 47 ppm/°C		
Above Tg 140 ppm/°C		
Dynamic Tensile Modulus	Dynamic Mechanical Thermal	FT-M019
@ -60°C 4500 MPa	Analysis using <1.5 mm thick	
@25°C 2900 MPa	Specimen	
@150°C 95 MPa		
@250°C 81 MPa		

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